

ANNOUNCEMENT
Special Issue of the IEEE Transactions on Plasma Science on
VACUUM DISCHARGE PLASMAS
Submission Deadline October 30, 2012
Publication Date August 2013

The XXVth International Symposium on Discharges and Electrical Insulation in Vacuum (ISDEIV 2012) was held on September 2 – 7, 2012, in Tomsk, Russia. The ISDEIV is an interdisciplinary forum in the field of electrical discharges and insulation in vacuum that brings together representatives from theoretical science, R&D and industry. The exchange of scientific results, and the discussions of ideas and new challenges offered good opportunity for progress in this field of activity. For this special issue we solicit papers presented at the symposium that reflect the most recent developments in the physics and technology of electrical discharges in vacuum and their applications.

The manuscripts submitted for publication in this special issue must not be identical to the proceedings manuscripts, but substantially revised and lengthened. They must be prepared following the style requirements of IEEE Transactions. In order to represent a full spectrum of activities in the field, we also encourage submissions that were not presented at the symposium, provided those contributions fit well to the following topics of the Call for Papers:

A: Breakdown and Flashover

1. Vacuum breakdown and pre-breakdown phenomena
2. Surface discharges and flashover phenomena
3. RF breakdown and multipactoring phenomena
4. High field effects in micro-electromechanical systems and nanostructures

B: Vacuum arcs

1. Switching in vacuum and related

phenomena

2. Interaction of vacuum arcs with magnetic field
3. Vacuum arc physics
4. Computer modeling and computer aided design
5. Pulse power physics and technology

C: Applications

1. Vacuum interrupters and their applications
2. Deposition of coatings by vacuum arc plasmas and related technologies
3. Electron, ion, neutron, X-ray and other beam and light sources
4. Accelerators and fusion reactor related issues
5. Space related technologies

All contributions should be submitted electronically through the IEEE Manuscript Central web site at: <http://mc.manuscriptcentral.com/tps-ieee> as described in the submission instructions <http://www.ieee.org/web/publications/authors/transjnl/index.html>. All papers will undergo a standard peer-review process typical for all IEEE Transactions and Journals.

Please direct questions to the Guest Editor for this Special Issue:

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ANNOUNCEMENT
Regular Issue of the IEEE Transactions on Dielectrics and Electrical Insulation
with an extended section on VACUUM INSULATION
Informal Submission Deadline October 30, 2012

Authors who are interested in having a manuscript published in the IEEE Transactions on Dielectrics and Electrical Insulation are advised to submit their manuscript as a regular paper. All contributions should be submitted electronically through the <http://www.cloznet.com/ieeetdei/ieeetdei.cfm> web site. The authors are invited to meet October 30, 2012, as an informal deadline for submission of manuscripts to enter their papers in the same issue. Authors are reminded that manuscripts must not be identical to the proceedings manuscripts but substantially revised and amended. They must be prepared following the style requirements of IEEE Transactions.